



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

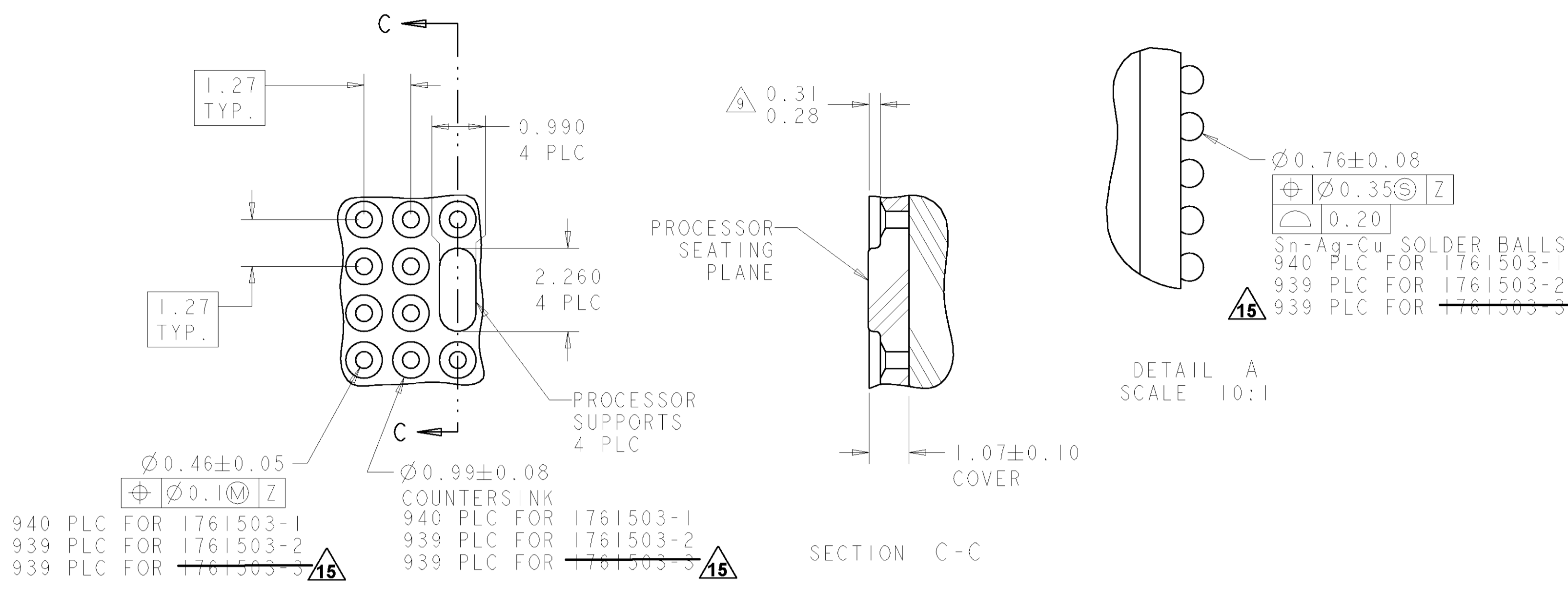
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

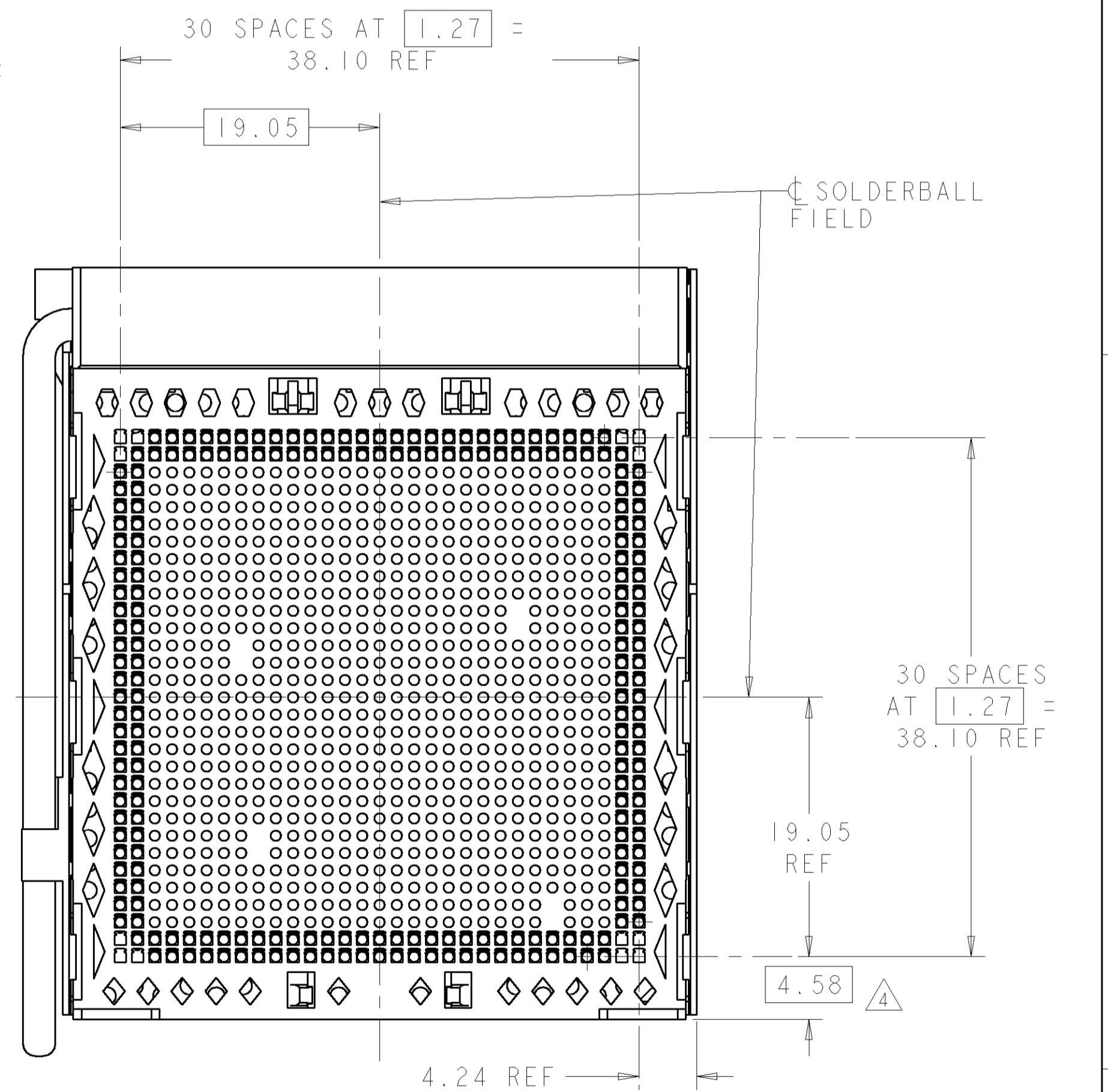
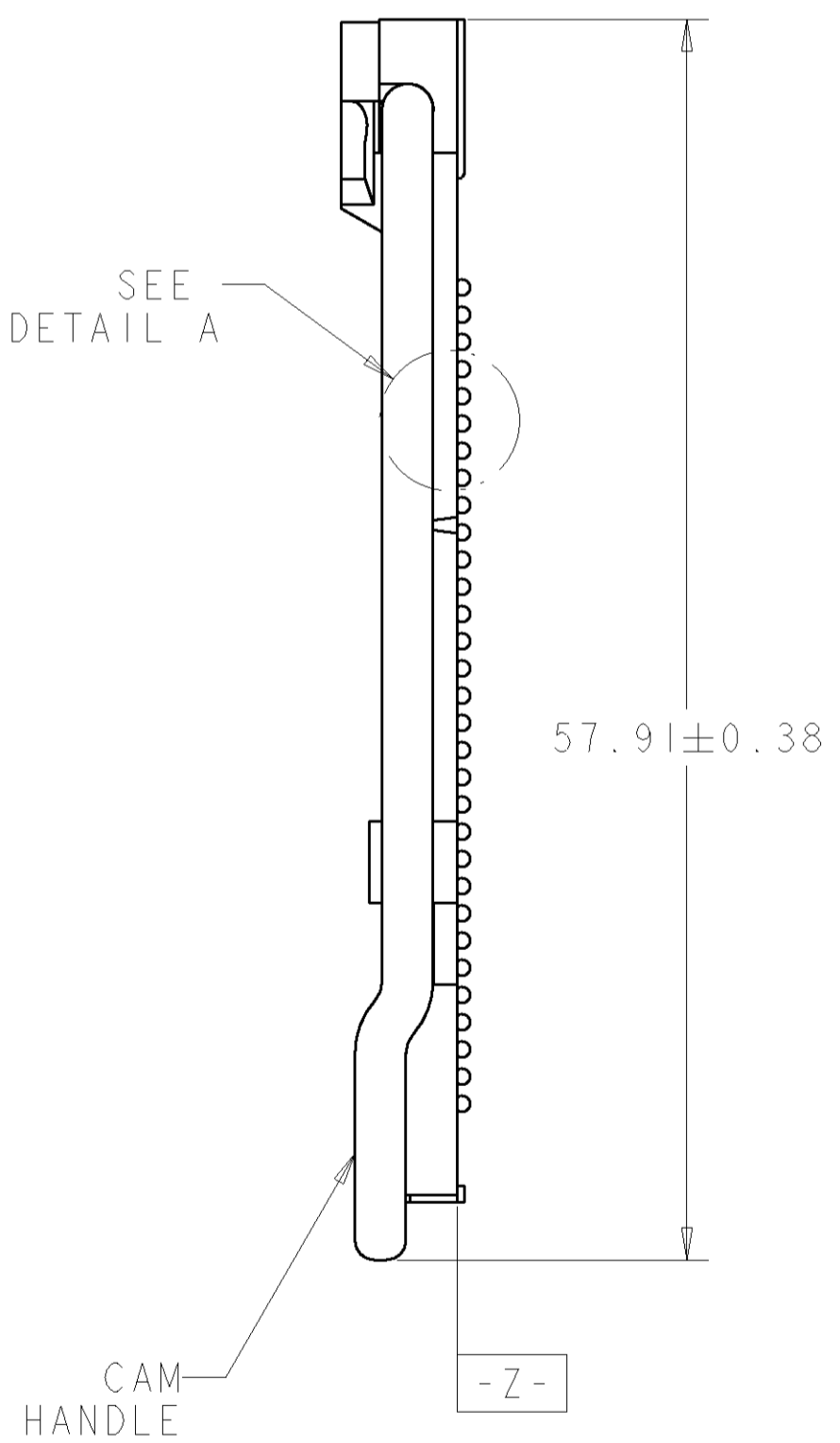
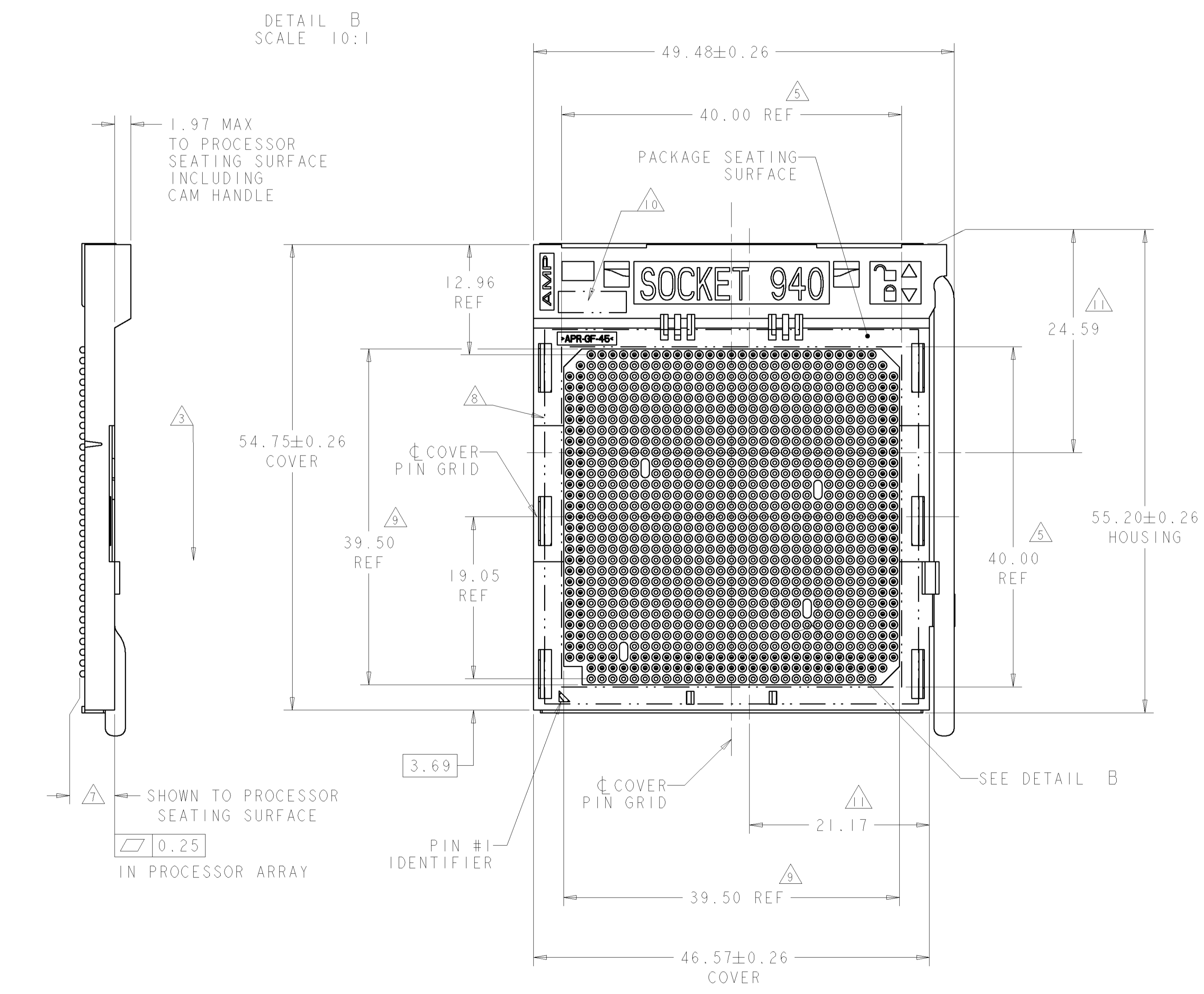
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC		REVISIONS			
NO	DATE	DESCRIPTION	DATE	BY	APP'D
D		REVISED PER ECR-08-002542	29JAN2008	SYJ	LSF
D1		REVISED PER ECO-09-025699	08DEC09	KK	AEG



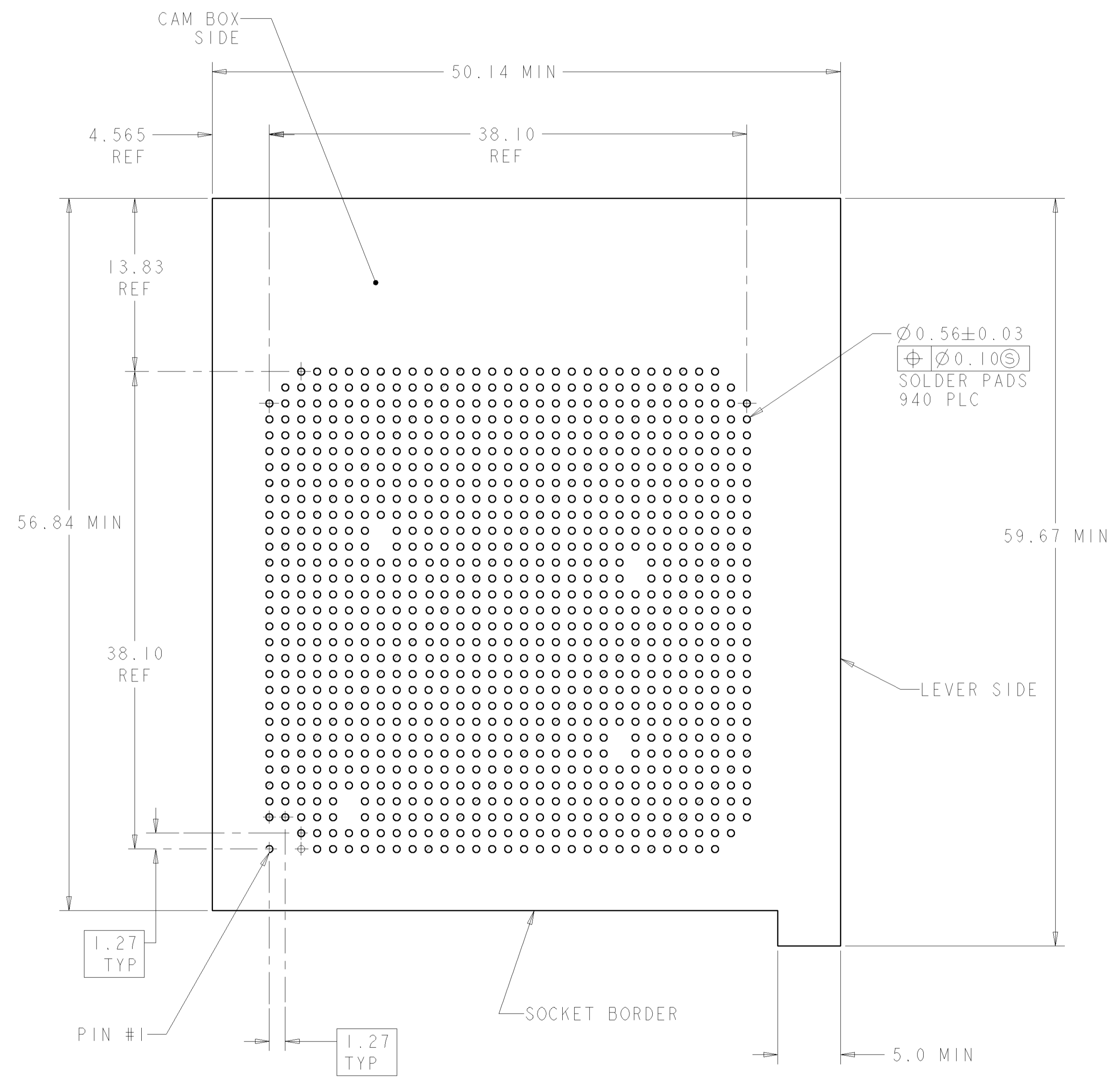
- △ HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, BLACK.
COVER: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, NATURAL;
CONTACT: COPPER ALLOY; HANDLE: STAINLESS STEEL.
- △ CONTACT: 0.76µm MIN GOLD IN CONTACT AREA, OVER 1.27µm MIN NICKEL ALL OVER.
- △ ACTUATION DIRECTION AS SHOWN 0.38 NOMINAL PROCESSOR MOVEMENT.
- △ THIS DIMENSION FOR FRONT ROW SOLDER BALLS.
- △ PROCESSOR OUTLINE.
- △ SOCKET IS DESIGNED FOR SINGLE SIDE PCB APPLICATION ONLY.
- △ SOCKET FINAL HEIGHT FROM PC BOARD TO PROCESSOR SEATING SURFACE IS, 4.35 MAX BEFORE SOLDER REFLOW AND 4.20 MAX AFTER SOLDER REFLOW.
- △ PICK-UP TAPE COVERING ALL CIRCUIT HOLES PROVIDED FOR PICK AND PLACE EQUIPMENT.
IMPORTANT: REMOVE TAPE BEFORE INSTALLING PROCESSOR.
- △ POCKET RECESS.
- △ DATE CODE MARKINGS APPROXIMATE AREA SHOWN.
- △ APPROXIMATE CENTER OF GRAVITY OF SOCKET ASSEMBLY
- △ PC BOARD LAYOUTS FOR 1761503-2, -3 AND -4 ARE EACH DIFFERENT THAN 1761503-1 IN AREAS CIRCLED.
- △ QUALIFICATION TEST REPORT 501-571.
- △ PART NUMBER HAS BEEN OBSOLETED.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



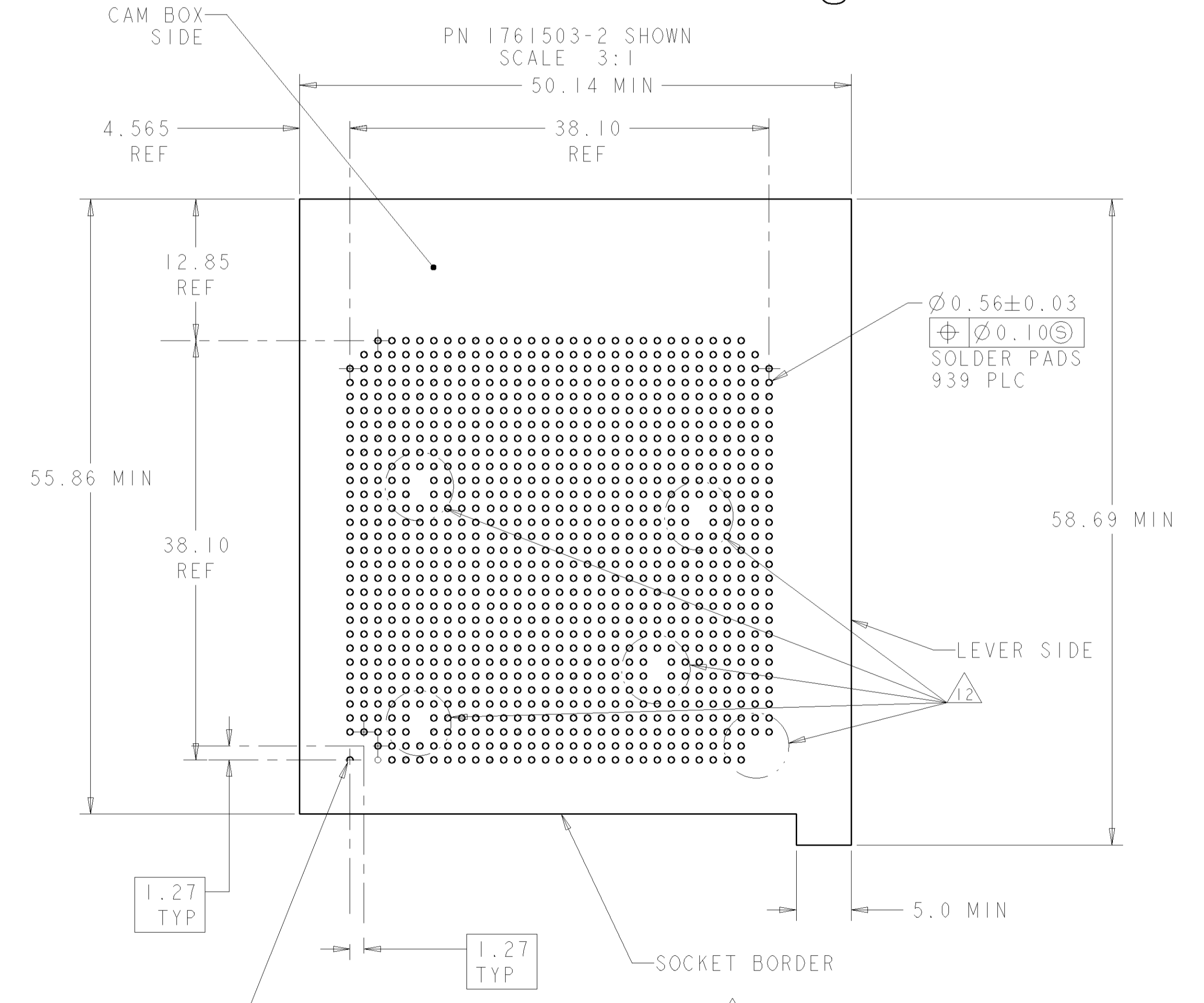
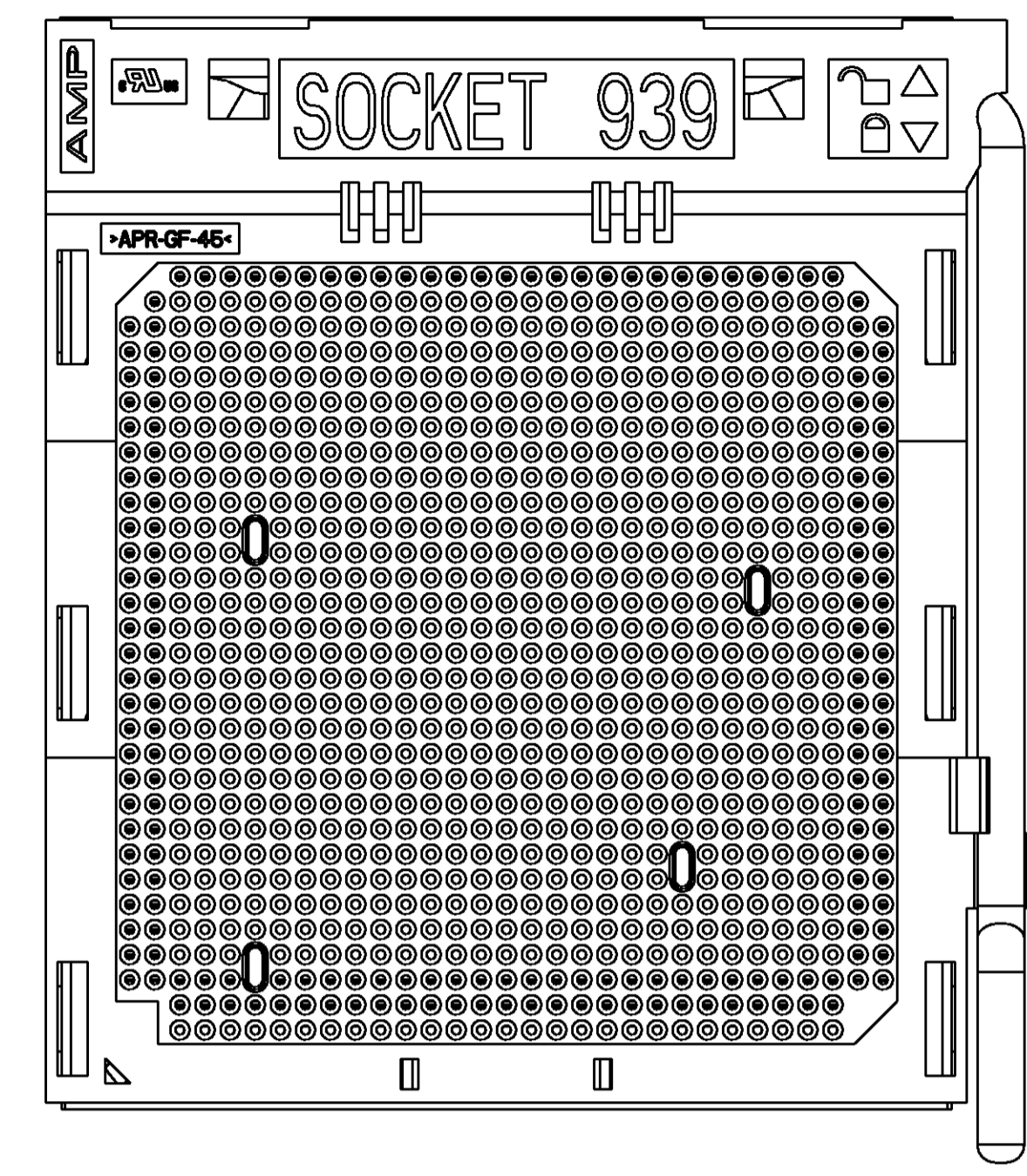
SEE VIEW AND PCB LAYOUT, SH3	1761503-4
SEE VIEW AND PCB LAYOUT, SH3	1761503-3
SEE VIEW AND PCB LAYOUT, SH 2	1761503-2
AS SHOWN, SH 1 AND PCB LAYOUT, SH 2	1761503-1
DESCRIPTION	PART NUMBER

15
OBSOLETE

DIMENSIONS: mm TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.31 5 PLC ±0.001 4 PLC ± ANGLES ± FINISH: △		DWN: 25OCT2004 BEC/DESIGNER: B. D. KUHNLY CHK: B. D. KUHNLY AP'D: B. D. KUHNLY PRODUCT SPEC: 108-51077 APPLICATION SPEC: 114-13092 WEIGHT: 14.1g CUSTOMER DRAWING	Tyco Electronics Corporation Singapore NAME: SOCKET PACKAGING 940/939 POSITION, SINGLE LEVER ACTUATED, ZIF, MICRO PGA, LF SIZE: A1 CAGE CODE: 00779 DRAWING NO: C=1761503 SCALE: 3:1 SHEET: 1 OF 4 REV: D1
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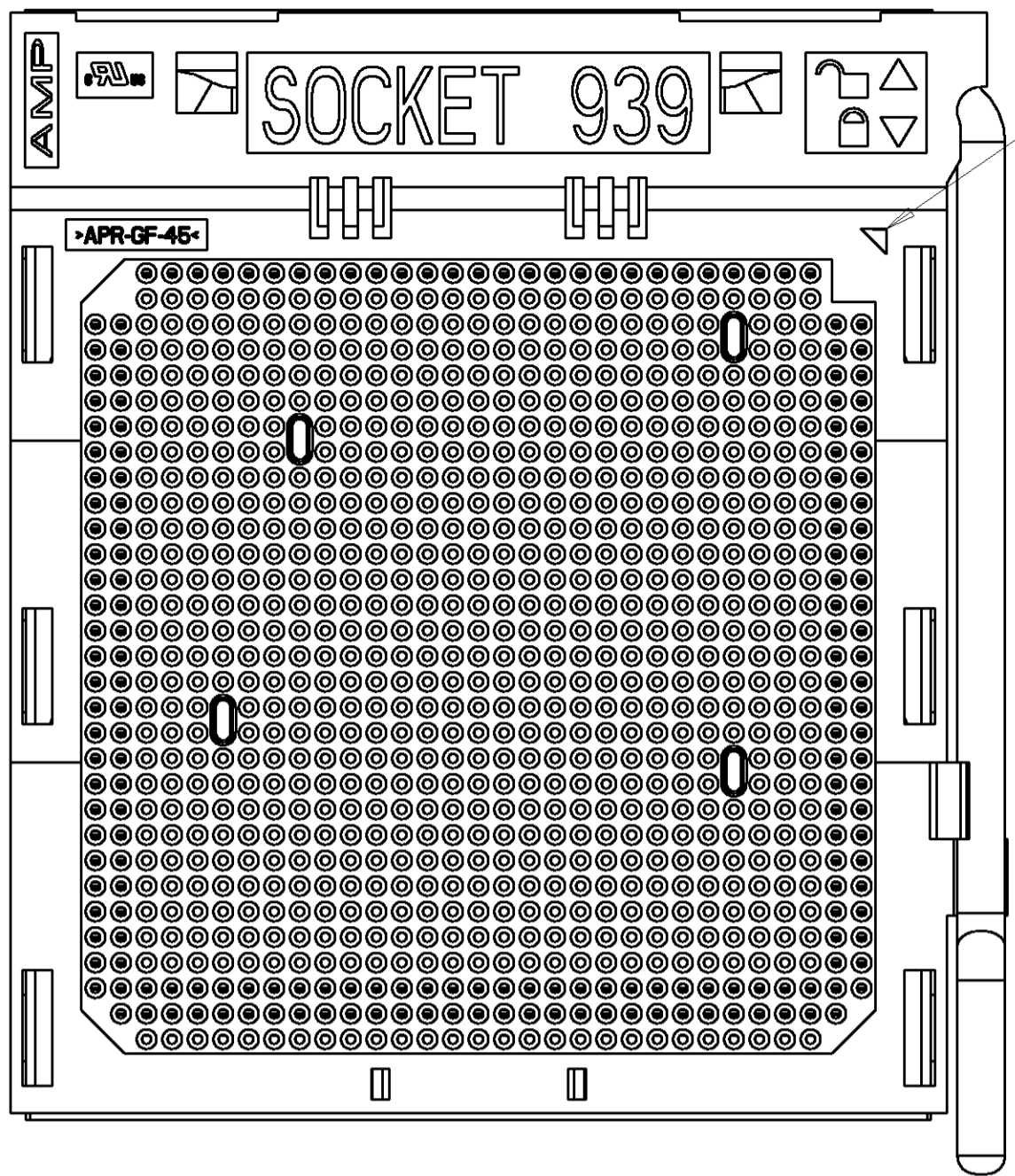
PC BOARD LAYOUT
 (FOR 1761503-1 940 POSITION ONLY)
 SCALE 4:1



PC BOARD LAYOUT
 (FOR 1761503-2 939 POSITION ONLY)
 SCALE 3:1

DIMENSIONS: mm 		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.01 3 PLC ±0.001 4 PLC ± ANGLES ±		DWN: 250CT2004 BEC/DESIGNER: 250CT2004 CHG: B. D. KUHNLY APVD: B. D. KUHNLY NAME: SOCKET 939 PRODUCT SPEC: 108-51077 APPLICATION SPEC: 114-13092 WEIGHT: 14.1g CUSTOMER DRAWING		Tyco Electronics Corporation Singapore NAME: SOCKET PACKAGING 940/939 POSITION, SINGLE LEVER ACTUATED, ZIF, MICRO PGA, LF SIZE: A1 CASE CODE: 00779 DRAWING NO: C=1761503 SCALE: 3:1 SHEET: 2 OF 4 REV: D1	
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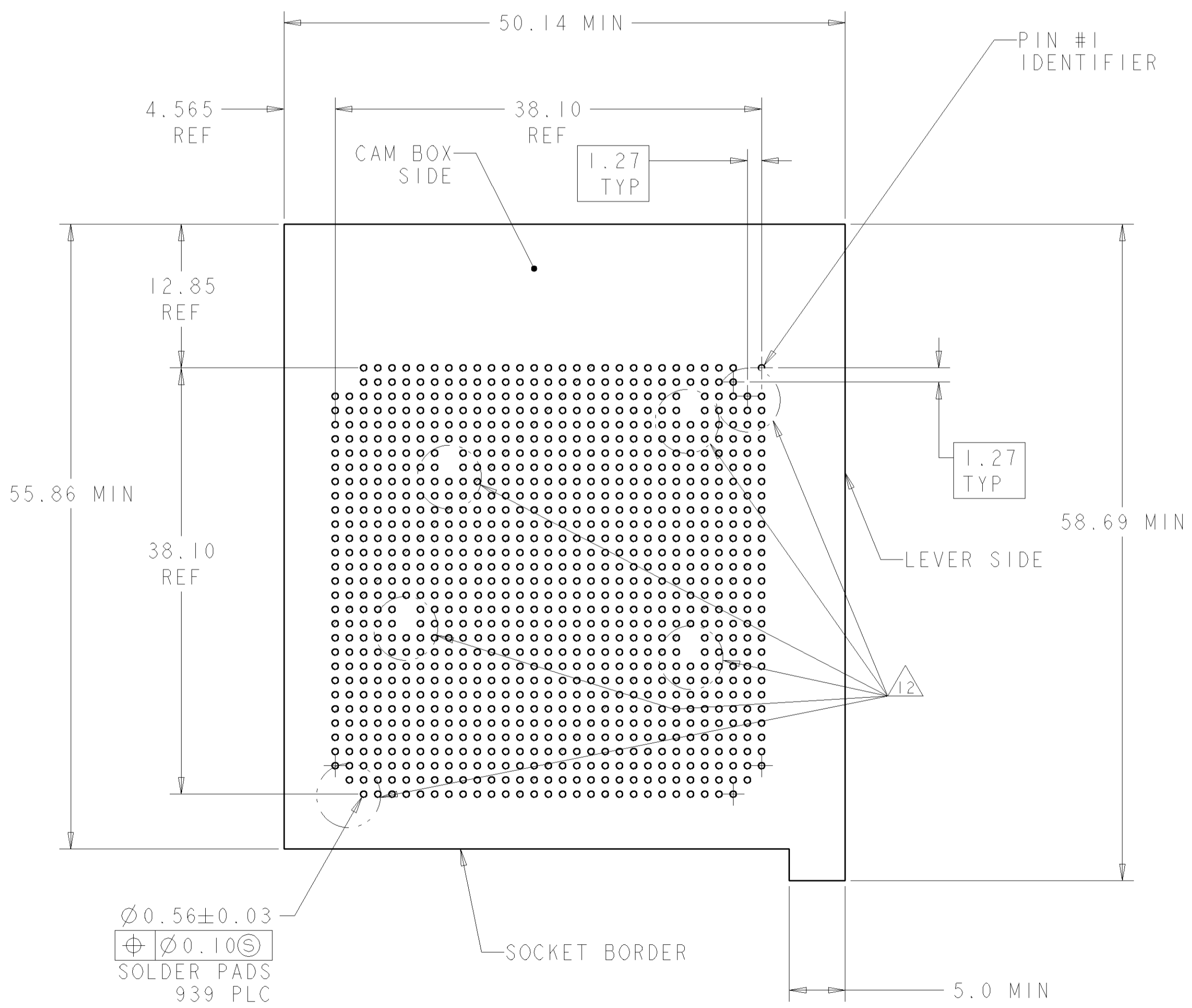
LOC	DIST	REVISIONS					
		P.	LTR	DESCRIPTION	DATE	DWN	APVD
DY	-	-	-	SEE SHEET 1	-	-	-



PIN #1 IDENTIFIER

SCALE 3:1

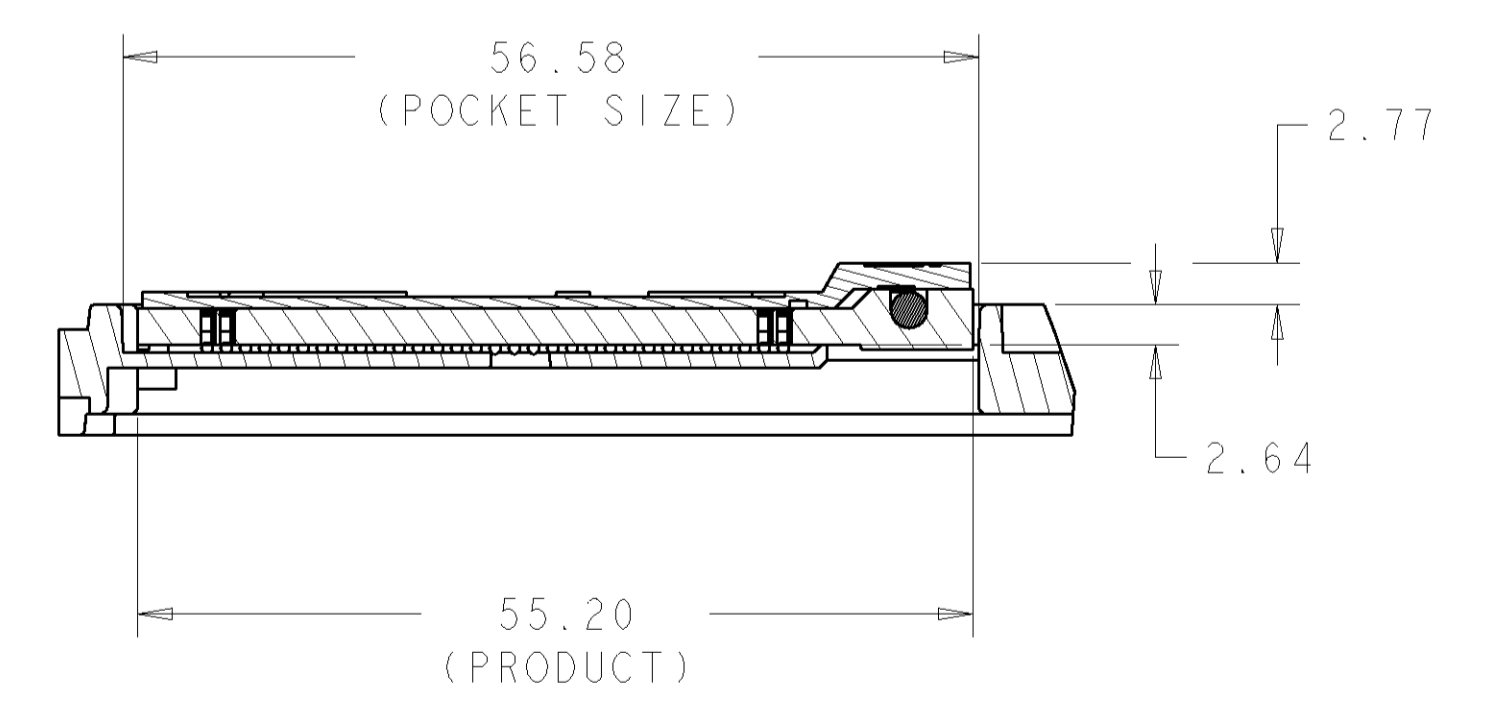
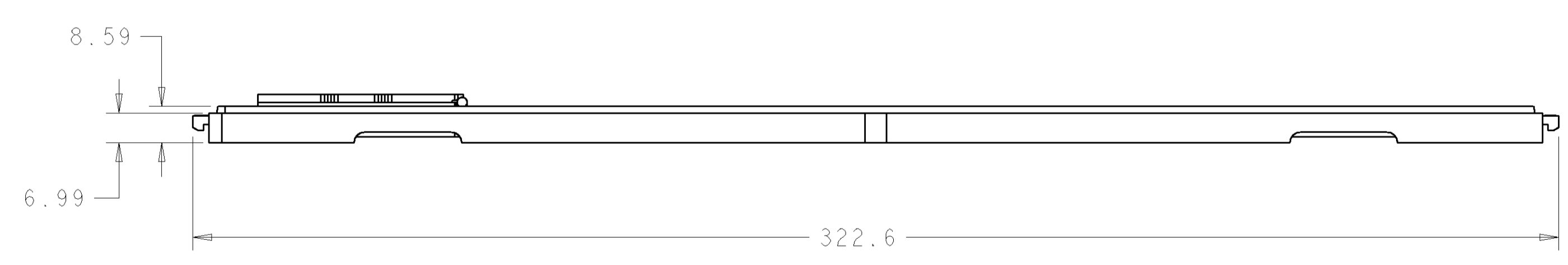
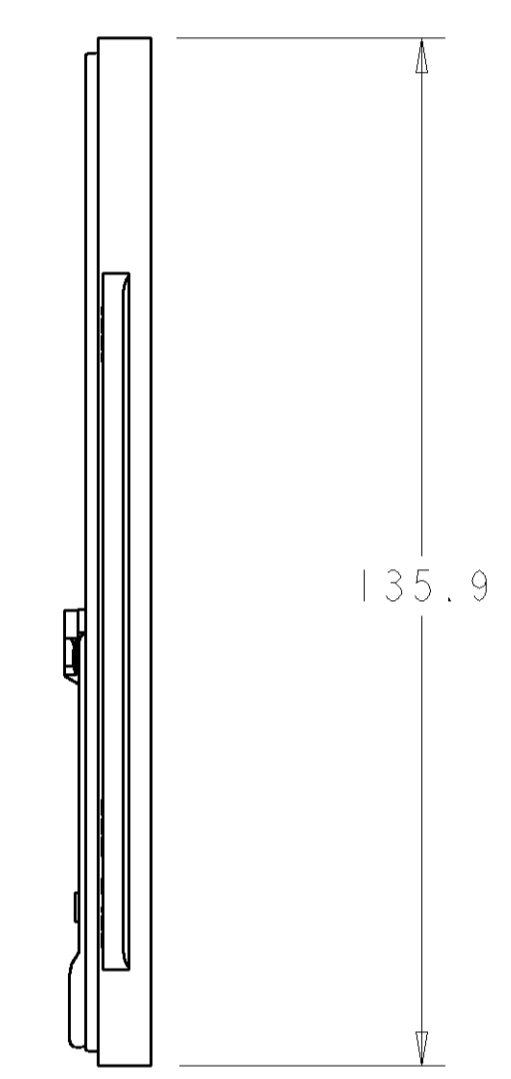
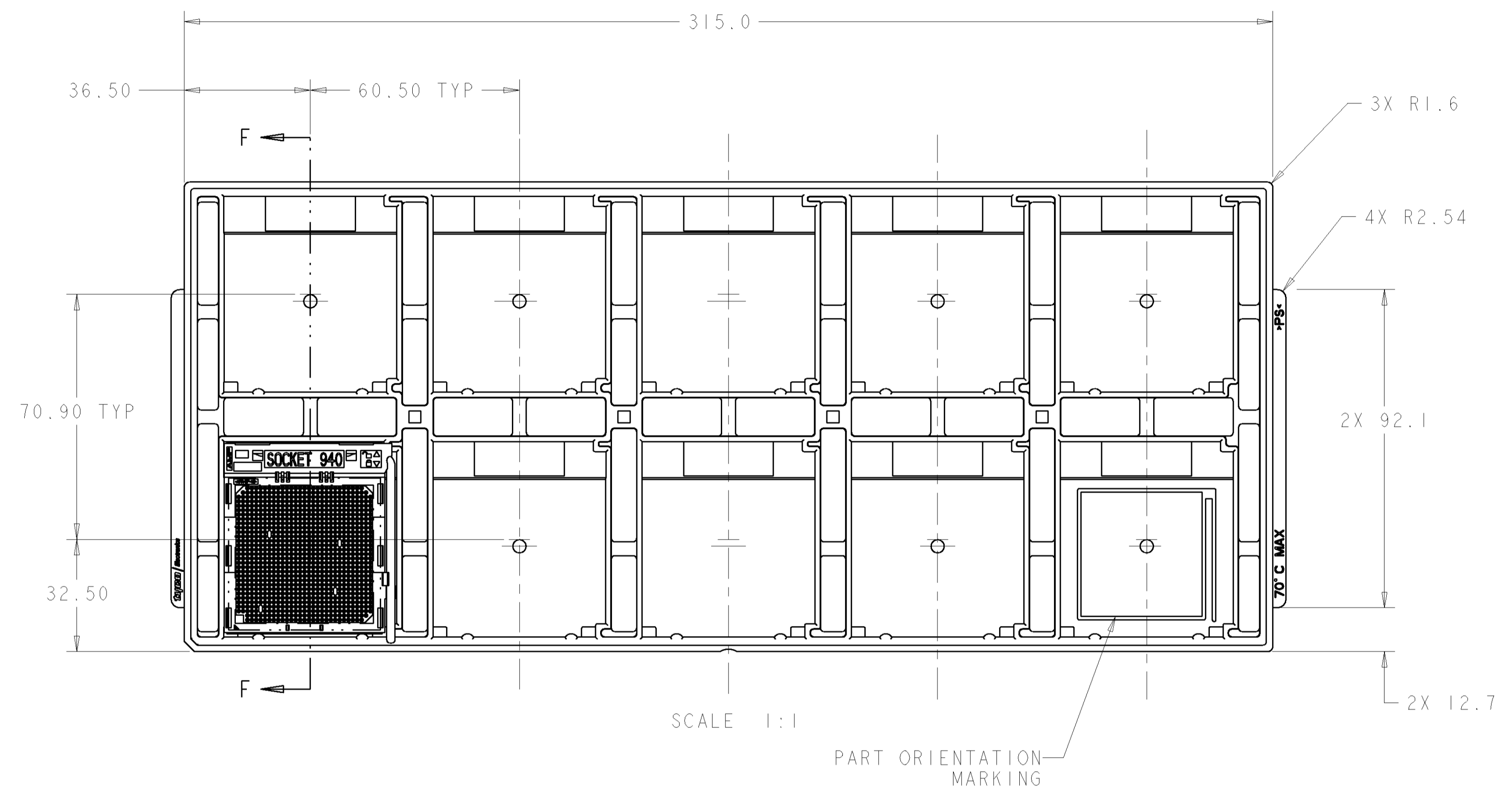
(SAME AS 1761503-2 EXCEPT CONTACT PATTERN AND POLARIZATION FEATURES ROTATED 180°)



PC BOARD LAYOUT
 (FOR 1761503-3 939 POSITION ONLY)
 SCALE 3:1

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.</small>		DWN: 25OCT2004 BEC/DESIGNER: B. D. KUHNLY CHK: B. D. KUHNLY APVD:		Tyco Electronics Corporation Singapore	
DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.01 3 PLC ±0.01 4 PLC ±0.001 ANGLE ±		NAME: SOCKET PACKAGING PRODUCT SPEC: 940/939 POSITION, SINGLE LEVER APPLICATION SPEC: 108-51077 ACTUATED, ZIF, MICRO PGA, LF	
MATERIAL: - FINISH: -		WEIGHT: 14.1g CUSTOMER DRAWING		SIZE: A1 CASE CODE: 00779 DRAWING NO: C=1761503 RESTRICTED TO: -	
				SCALE: 3:1 SHEET 3 OF 4 REV: D1	

LOC	DIST	REVISIONS			
APVD	DATE	BY	DESCRIPTION	DATE	DWN
DY	-	-	SEE SHEET 1	-	-



SECTION F-F
 ROTATED 90°
 SCALE 2:1

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. IT IS SUBJECT TO CHANGE AND THE CUSTOMER'S ORGANIZATION SHALL BE CONTACTED FOR THE LATEST REVISION.</small>		DWN: 25OCT2004 BEC/DESIGNER: CHG: B. D. KUHNLY APVD: B. D. KUHNLY	Tyco Electronics Corporation Singapore
DIMENSIONS: mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.01 2 PLC ±0.01 3 PLC ±0.001 4 PLC ± ANGLES ± FINISH	NAME: SOCKET PACKAGING PRODUCT SPEC: 940/939 POSITION, SINGLE LEVER APPLICATION SPEC: ACTUATED, ZIF, MICRO PGA, LF SIZE: 114-13092 WEIGHT: 14.1g CUSTOMER DRAWING	SCALE: 3:1 SHEET: 4 OF 4 REV: D1